CLAIMS

1. (Original) A thick film composition comprising:

a) functional component;

b) PVDF/HFP polymer resin, a copolymer of PVDF/HFP polymer resin, or mixtures thereof; dissolved in

c) organic solvent.

with the provisos that the PVDF/HFP resin has i) a melt viscosity of 0.2-0.7 kPoise and ii) a DSC melt temperature in the range of 85-98°C.

2. (Original) The composition of Claim 1 wherein said functional component is selected from silver, carbon, graphite or mixtures thereof.

3. (Original) The composition of Claim 1 wherein said functional component is selected from phosphor, phosphor-containing particles, or mixtures thereof.

4. (Original) The composition of Claim 1 wherein said functional component is selected from $BaTiO_3$, TiO_2, or mixtures thereof.

5. (Original) The composition of Claim 1 wherein the PVDF/HFP resin contains 12-16 mole% of hexafluoropropylene (HFP) in the total resin composition.

6. (Original) The composition of Claim 1 further comprising an adhesion promoter.

7. (Original) The composition of Claim 1 further comprising a flow additive.

8. (Currently amended) The composition of Claim 1 wherein the organic solvent is selected from the group ~~comprising~~ consisting of carbitol acetate.

9. (Currently amended) The use of the composition of any one of Claims 1-8 in the formation of an electroluminescent panel, comprising:

(a) providing a substrate;

(b) depositing at least one layer of a phosphor-containing thick film composition onto said substrate;

(c) depositing a least one layer of a dielectric thick film composition onto the layer of (b); and

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(d) depositing at least one layer of a conductive thick film composition onto the layer of (c);

wherein at least one layer of (b), (c) or (d) contains a PVDF/HFP polymer resin, copolymer of a PVDF/HFP polymer resin, or mixtures thereof which has i) a melt viscosity of 0.2-0.7 kPoise and ii) a DSC melt temperature in the range of 85-98°C.

10. (Withdrawn) A method of forming an electroluminescent panel comprising:

(e) providing a substrate;

(f) depositing at least one layer of a phosphor-containing thick film composition onto said substrate;

(g) depositing a least one layer of a dielectric thick film composition onto the layer of (b); and

(h) depositing at least one layer of a conductive thick film composition onto the layer of (c);

wherein at least one layer of (b), (c) or (d) contains a PVDF/HFP polymer resin, copolymer of a PVDF/HFP polymer resin, or mixtures thereof which has i) a melt viscosity of 0.2-0.7 kPoise and ii) a DSC melt temperature in the range of 85-98°C.

11. (Original) An electroluminescent panel utilizing the composition of any one of Claims 1-9.

12. (Currently amended) The electroluminescent panel formed ~~by the method of Claim 10~~ by a method of forming an electroluminescent panel comprising:

(i) providing a substrate;

(j) depositing at least one layer of a phosphor-containing thick film composition onto said substrate;

(k) depositing a least one layer of a dielectric thick film composition onto the layer of (b); and

(l) depositing at least one layer of a conductive thick film composition onto the layer of (c);

wherein at least one layer of (b), (c) or (d) contains a PVDF/HFP polymer resin, copolymer of a PVDF/HFP polymer resin, or mixtures thereof which has i) a melt viscosity of 0.2-0.7 kPoise and ii) a DSC melt temperature in the range of 85-98°C, wherein the panel is the panel of Claim 9.

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